高速傳输軟性基板用低粗糙度高彎折性电解铜箔

Very Low Profile of high bending property copper foil

3EC-M2S-HTE™ SP2 & 3EC-M2S-HTE™ SP3

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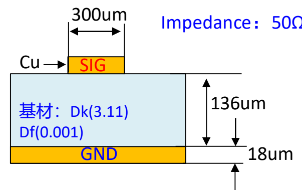
Suitable for High Speed High Frequency and Fine pattern FPCBs design with excellent Bending Performance.

適合搭配MPI，信號傳輸損耗低，效果好

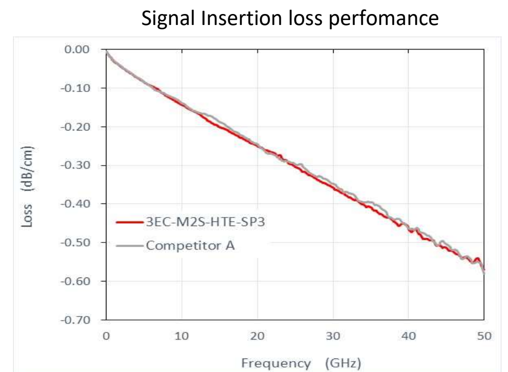
Excellent Signal Insertion lost performance with Modified PI.

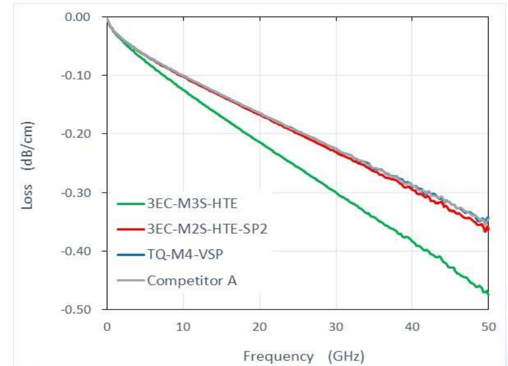
剝離强度高

Good Bonding strength.



Signal Insertion loss perfomance





3EC-M2S-HTE SP2/SP3

Average crystal size: 6.5μm

※After 180C, 1hr 3μm

Class Ⅲ

Average crystal size: 2.5μm

※After 180C, 1hr 3μm

		Surface roughness Lam. Side ［μm］	Cross Section Image	Thickness ［μm］
Normal Profile (Reference)	3EC-M3S-HTE	Rz 2.5		12 μm
Very Low Profile	3EC-M2S-HTE-SP2	Rz ~ 1.4		18 μm
Super Low Profile	3EC-M2S-HTE-SP3	Rz 0.9~1.1		9um,12 μm,18um

* Mass Production in Mitsui Copper Foil Malaysia plant.

Excellent Copper Foil characteristic for Advance Flexible Board application.

三井金屬特有的高彎折性铜箔加上低粗糙度處理。

- Mitsui proprietary high bending property copper foil with very low profile treatment.

應用于高频高速上表现超低損耗。

- Improved Signal lost performance in High speed High frequency application.

產能高，足以满足客户量产需求。

- Good track record of reliable and advance production capability to fulfil customers' volume requirement.

三井金属